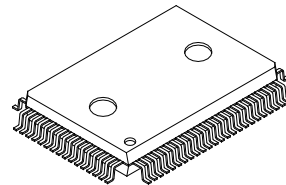


CMOS 8-bit Single Chip Microcomputer**Description**

The CXP82532/82540 microcomputer is composed of a CPU, ROM RAM, and I/O ports. These chips feature many other high-performance circuits in a single-chip CMOS design, including an A/D converter, serial interface, timer/counter, time-base timer, capture timer/counter, fluorescent display controller/driver, remote control receiver.

This device also includes a power-on reset function and sleep/stop functions which can be used to achieve low power consumption.

80 pin QFP (Plastic)

**Features**

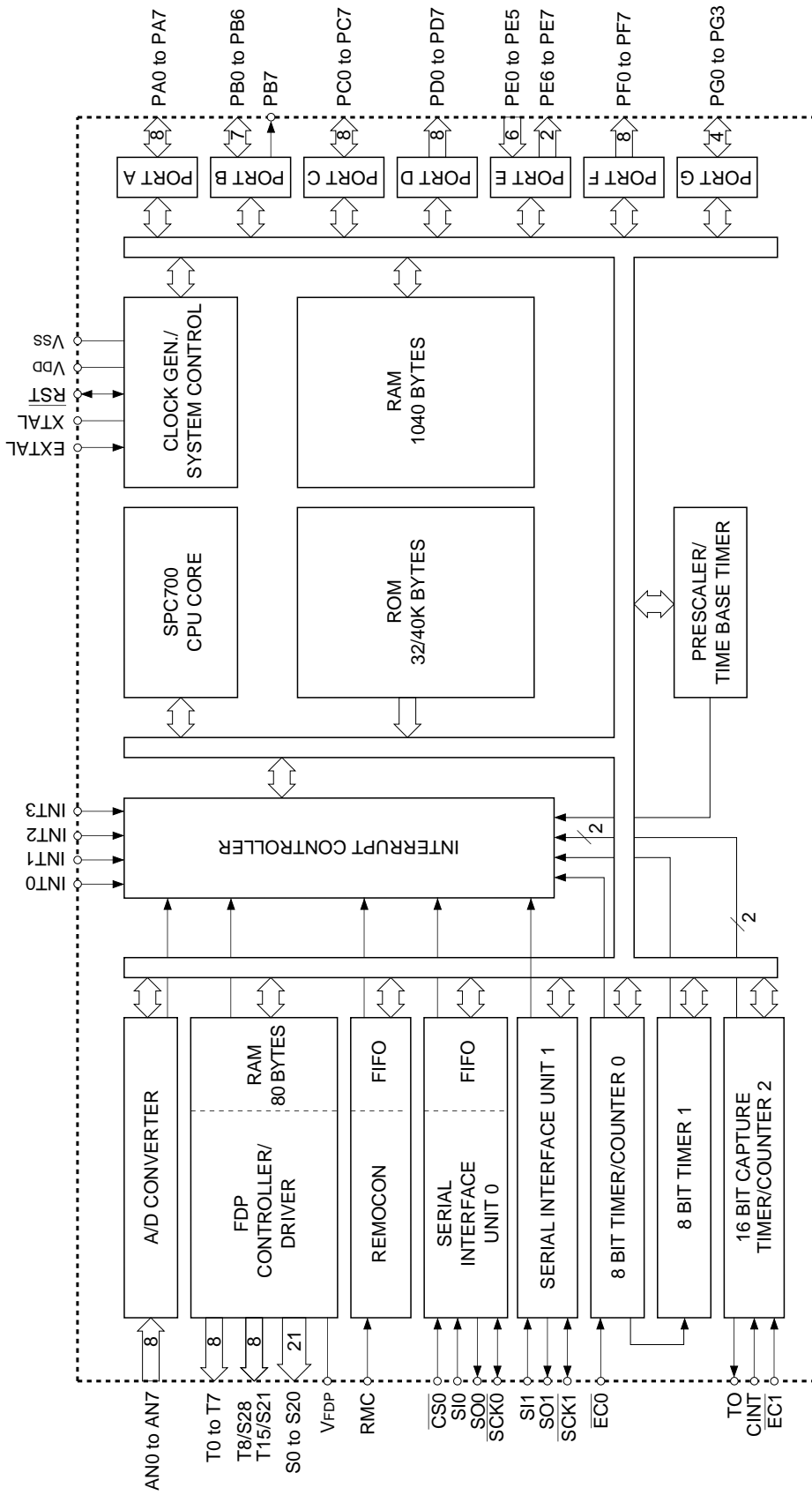
- Instruction set which supports a wide array of data types
 - 213 types of instructions which include 16-bit calculations, multiplication and division arithmetic, and boolean bit operations.
- Minimum instruction cycle 400ns for 10MHz operation
- On-chip ROM 32K bytes (CXP82532)
 40K bytes (CXP82540)
- On-chip RAM 1120 bytes (Including fluorescent display data area)
- Peripheral functions:
 - A/D converter 8-bit, 8-channel, successive approximation system
(conversion time 32 μ s/10MHz)
 - Serial interface On-chip 8-bit, 8-stage FIFO (1 to 8 bytes auto transfer) 1 channel
8-bit clock synchronized 1 channel
 - Timers 8-bit timer
8-bit timer/counter
19-bit time-base timer
16-bit capture timer/counter
 - Fluorescent display controller/driver Maximum of 336 segment display available
1 to 16 digits dynamic display
Dimmer function
High voltage tolerance output (40V)
On-chip pull-down resistor (Mask option)
 - Remote control receiver circuit
 - On-chip noise elimination circuit
 - On-chip 6 stage FIFO 8-bit pulse measurement counter
- Interrupts 14 factors, 15 vectors multi-interruption possible
- Standby mode Sleep/stop
- Package 80-pin plastic QFP
- Piggyback/evaluator CXP82500 80-pin ceramic QFP

Structure

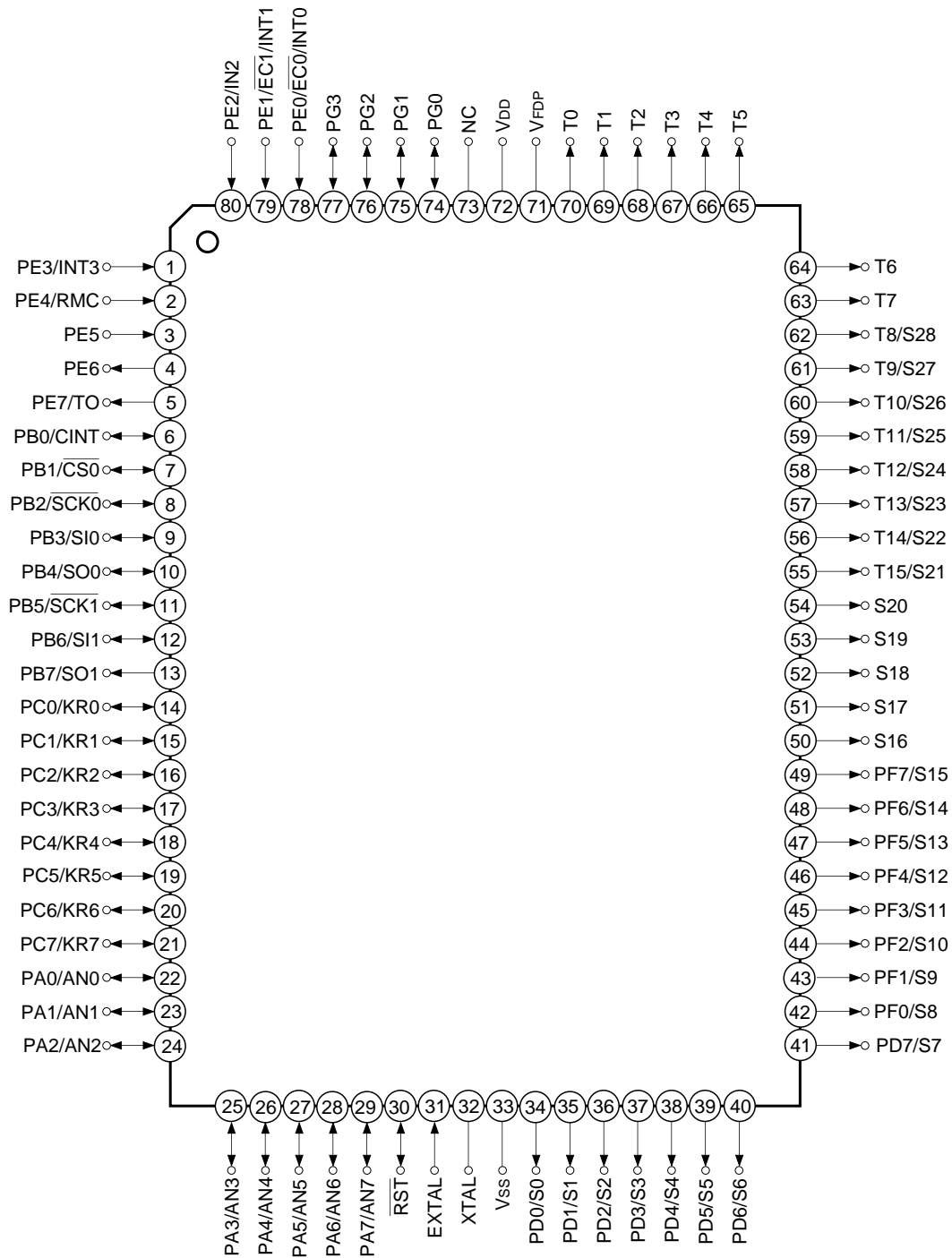
Silicon gate CMOS IC

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Block Diagram



Pin Assignment (Top View)



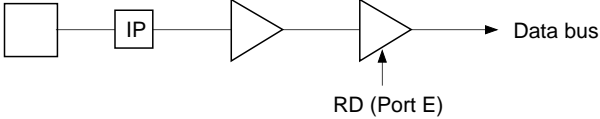
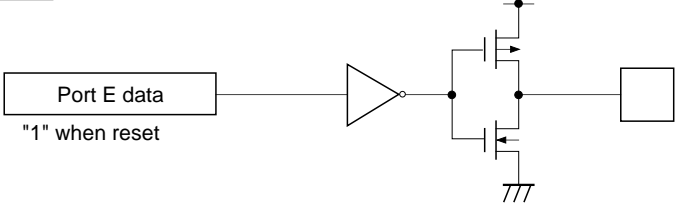
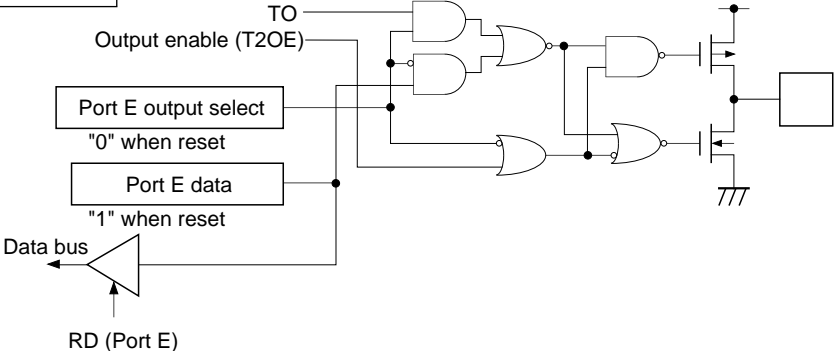
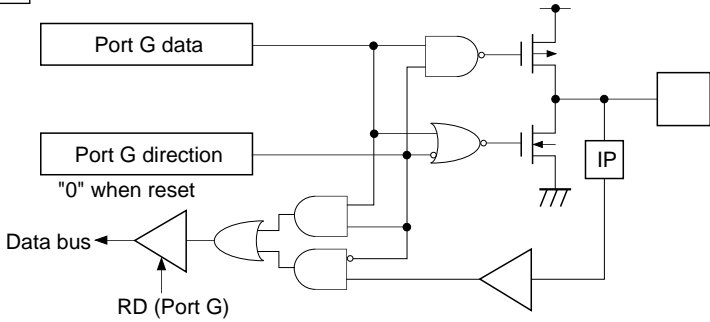
Note) NC (Pin 73) is always connected to VDD.

Pin Description

Symbol	I/O	Description	
PA0/AN0 to PA7/AN7	I/O/Analog input	(Port A) 8-bit port; single bit addressable. (8 pins)	Analog input to A/D converter. (8 pins)
PB0/CINT	I/O/Input	(Port B) Single bit addressable from amongst lower 7 bits; highest bit (PB7) dedicated to output. (8 pins)	External capture input for 16-bit timer/counter.
PB1/ $\overline{\text{CS}}_0$	I/O/Input		Chip select input for serial interface (CH0).
PB2/ $\overline{\text{SCK}}_0$	I/O/I/O		Serial clock (CH0) input/output.
PB3/SI0	I/O/Input		Serial data (CH0) input.
PB4/SO0	I/O/Output		Serial data (CH0) output.
PB5/ $\overline{\text{SCK}}_1$	I/O/I/O		Serial clock (CH1) input/output.
PB6/SI1	I/O/Input		Serial data (CH1) input.
PB7/SO1	Output/Output		Serial data (CH1) output.
PC0/KR0 to PC7/KR7	I/O/Input		(Port C) 8-bit port; single bit addressable. Can provide 12mA sink current. (8 pins)
PE0/INT0/ $\overline{\text{EC}}_0$	Input/Input/Input	(Port E) 8-bit port with lower 6 bits dedicated to input and upper 2 bits dedicated to output. (8 pins)	Input for external interrupt requests. (4 pins)
PE1/INT1/ $\overline{\text{EC}}_1$	Input/Input/Input		
PE2/INT2	Input/Input		Input for remote control receiver circuit.
PE3/INT3	Input/Input		
PE4/RMC	Input/Input		
PE5	Input		
PE6	Output		Output pin for 16-bit timer/counter rectangular waveform.
PE7/TO	Output/Output		
PG0 to PG3	I/O	(Port G) 4-bit input/output port; single bit addressable. (4 pins)	
PF0/S8 to PF7/S15	Output/Output	(Port F) 8-bit dedicated output port. (8 pins)	Segment signal output for FDP.
S16 to S20	Output	Segment signal output for FDP.	
T8/S28 to T15/S21	Output/Output	Dual purpose output for FDP timing and segment signals.	
T0 to T7	Output	Timing signal output for FDP.	
PD0/S0 to PD7/S7	Output/Output	(Port D) 8-bit dedicated output port. (8 pins)	Segment signal output for FDP.

Symbol	I/O	Description
V _{FDP}		Provides voltage for FDP when on-chip resistor is selected under mask option.
EXTAL	Input	Connection for system clock oscillation crystal. When using an external clock, input normal signal to EXTAL and reverse phase signal to the XTAL pin.
XTAL	Output	
$\overline{\text{RST}}$	I/O	System reset, active "L". The $\overline{\text{RST}}$ pin is an input/output pin which outputs a "L" level from the on-chip power-on reset circuit when the power is turned on. (Mask option)
NC		NC pin is always connected to V _{DD} .
V _{DD}		Positive power supply pin.
V _{SS}		GND

Pin	Circuit format	When reset
<p>PB4/SO0</p> <p>1 pin</p>	<p>Port B</p>	<p>Hi-Z</p>
<p>PB7/SO1</p> <p>1 pin</p>	<p>Port B</p> <p>*Pull-up transistor about 200kΩ</p>	<p>High level</p>
<p>PC0/KR0 to PC7/KR7</p> <p>8 pins</p>	<p>Port C</p> <p>*Capable of driving 12mA large current</p>	<p>Hi-Z</p>
<p>PE0/EC0/INT0 PE1/EC1/INT1 PE2/INT2 PE3/INT3 PE4/RMC</p> <p>5 pins</p>	<p>Port E</p>	<p>Hi-Z</p>

Pin	Circuit format	When reset
<p>PE5</p> <p>1 pin</p>	<p>Port E</p> 	<p>Hi-Z</p>
<p>PE6</p> <p>1 pin</p>	<p>Port E</p> 	<p>High level</p>
<p>PE7/TO</p> <p>1 pin</p>	<p>Port E</p> 	<p>High level</p>
<p>PG0 to PG3</p> <p>4 pins</p>	<p>Port G</p> 	<p>Hi-Z</p>

Pin	Circuit format	When reset
<p>Port D Port F</p> <p>PD0/S0 to PD7/S7</p> <p>PF0/S8 to PF7/S15</p> <p>16 pins</p>		<p>Hi-Z or Low level (when PD resistor is connected)</p>
<p>S16 to S20 T15/S21 to T8/S28 T0 to T7</p> <p>21 pins</p>		<p>Hi-Z or Low level (when PD resistor is connected)</p>
<p>EXTAL XTAL</p> <p>2 pins</p>	<p>*Diagram shows circuit construction for oscillation.</p> <p>*During stop feedback resistor is disconnected.</p>	<p>Oscillation</p>
<p>$\overline{\text{RST}}$</p> <p>1 pin</p>		<p>Low level</p>

Absolute Maximum Ratings

(V_{SS} = 0V)

Item	Symbol	Rating	Unit	Remarks
Supply voltage	V _{DD}	-0.3 to +7.0	V	
Input voltage	V _{IN}	-0.3 to +7.0* ¹	V	
Output voltage	V _{OUT}	-0.3 to +7.0* ¹	V	
Display output voltage	V _{OD}	V _{DD} - 40 to V _{DD} + 0.3	V	As P channel transistor is open drain, V _{DD} voltage is determined as standard.
High level output current	I _{OH}	-5	mA	Other than display output pins* ² : per pin
	I _{ODH1}	-15	mA	Display outputs S0 to S20: per pin
	I _{ODH2}	-35	mA	Display outputs T0 to T7, T8/S28 to T15/S21: per pin
High level total output current	∑I _{OH}	-40	mA	Total of other than display output pins
	∑I _{ODH}	-100	mA	Total of display output pins
Low level output current	I _{OL}	15	mA	Port 1 pin
	I _{OLC}	20	mA	Large current port pin * ³
Low level total output current	∑I _{OL}	100	mA	Entire pin total
Operating temperature	T _{opr}	-20 to +75	°C	
Storage temperature	T _{stg}	-55 to +150	°C	
Allowable power dissipation	P _D	600	mW	

*¹ V_{IN} and V_{OUT} cannot exceed V_{DD} + 0.3V.

*² Rating for output current of general input/output port.

*³ The large current drive transistor is an N-channel transistor of Port C.

Note) If the absolute maximum ratings are exceeded, the LSI could reach permanent breakdown. Also, observing recommended operating conditions is desirable; otherwise, the LSI's reliability could be affected.

Recommended Operating Conditions

(V_{SS} = 0V)

Item	Symbol	Min.	Max.	Unit	Remarks
Supply voltage	V _{DD}	4.5	5.5	V	High-speed mode (1/2, 1/4 clock) guaranteed range during operation
		3.5	5.5		Low-speed mode (1/16 clock) guaranteed range during operation
		2.5	5.5		Guaranteed data hold range during stop
High level input voltage	V _{IH}	0.7V _{DD}	V _{DD}	V	*1
	V _{IHS}	0.8V _{DD}	V _{DD}	V	Hysteresis input*2
	V _{IHEX}	V _{DD} - 0.4	V _{DD} + 0.3	V	EXTAL pin*3
Low level input voltage	V _{IL}	0	0.3V _{DD}	V	*1
	V _{ILS}	0	0.2V _{DD}	V	Hysteresis input
	V _{ILEX}	-0.3	0.4	V	EXTAL pin*3
Operating temperature	T _{opr}	-20	+75	°C	

*1 All regular input ports (PA, PB3, PB4, PB6, PC, PE5, PG).

*2 For pins \overline{RST} , \overline{CINT} , $\overline{CS0}$, $\overline{SCK0}$, $\overline{SCK1}$, $\overline{EC0/INT0}$, $\overline{EC1/INT1}$, INT2, INT3, RMC.

*3 Rating only for external clock input.

Electrical Characteristics

DC Characteristics

(Ta = -20 to +75°C, Vss = 0V)

Item	Symbol	Pins	Conditions	Min.	Typ.	Max.	Unit
High level output voltage	V _{OH}	PA, PB, PC, PE6, PE7, PG, RST*1 (for V _{OL} only)	V _{DD} = 4.5V, I _{OH} = -0.5mA	4.0			V
			V _{DD} = 4.5V, I _{OH} = -1.2mA	3.5			V
Low level output voltage	V _{OL}		V _{DD} = 4.5V, I _{OL} = 1.8mA			0.4	V
			V _{DD} = 4.5V, I _{OL} = 3.6mA			0.6	V
Input current	I _{IHE}	EXTAL	V _{DD} = 5.5V, V _{IH} = 5.5V	0.5		40	μA
	I _{IIE}		V _{DD} = 5.5V, V _{IL} = 0.4V	-0.5		-40	μA
	I _{ILR}	RST*2	V _{DD} = 5.5V, V _{IL} = 0.4V	-1.5		-400	μA
Display output current	I _{OH}	S0 to S20	V _{DD} = 4.5V V _{OH} = V _{DD} - 2.5V	-8			mA
		S21/T15 to S28/T8 T0 to T7		-20			mA
Open drain output leak current (P-CH Tr off state)	I _{IOL}	S0 to S20 S21/T15 to S28/T8 T0 to T7	V _{DD} = 5.5V V _{OL} = V _{DD} - 35V V _{FDP} = V _{DD} - 35V			-20	μA
Pull-down resistor*3	R _L	S0 to S20 S21/T15 to S28/T8 T0 to T7	V _{DD} = 5V V _{OD} - V _{FDP} = 30V	60	100	270	kΩ
Input/output leak current	I _{Iz}	PA to PC, PE, PG, RST*2	V _{DD} = 5.5V V _I = 0, 5.5V			±10	μA
Supply current*4	I _{DD1}	V _{DD}	V _{DD} = 5.5V High-speed mode (1/2 clock) operation 10MHz crystal oscillator (C ₁ = C ₂ = 15pF)		25	40	mA
	I _{DDSL}				3	8	mA
	I _{DDST}					10	μA
Input capacitance	C _{IN}	For pins other than S0 to S28, T0 to T7, PB7, PE6, PE7, V _{DD} , V _{SS} , V _{FDP}	1MHz clock 0V other than measured		10	20	pF

*1 RST pin is rated only when the power-on circuit is selected under the mask option.

*2 RST pin is rated for input current when the pull-up resistor is selected; otherwise it is rated for leak current.

*3 Applies when the on-chip pull-down resistor is selected under the mask option.

*4 All output pins are left open.

AC Characteristics

(1) Clock timing

(Ta = -20 to +75°C, VDD = 4.5 to 5.5V, VSS = 0V)

Item	Symbol	Pins	Conditions	Min.	Max.	Unit
System clock frequency	fc	XTAL EXTAL	Fig. 1, Fig. 2	1	10	MHz
System clock input pulse width	t _{XL} , t _{XH}	EXTAL	Fig. 1, Fig. 2 External clock driver	45		ns
System clock input rising and falling times	t _{CR} , t _{CF}	EXTAL	Fig. 1, Fig. 2 External clock driver		200	ns
Event count input clock pulse width	t _{EH} , t _{EL}	$\overline{EC0}$, EC1	Fig. 3	t _{sys} + 50*1		ns
Event count input clock rising and falling times	t _{ER} , t _{EF}	$\overline{EC0}$, EC1	Fig. 3		20	ms

*1 t_{sys} is determined by the upper two bits of the clock control register (Address: 00FEH; CPU clock selected) resulting in one of the 3 following values:
 t_{sys} [ns] = 2000/fc (Upper 2 bits = "00"), 4000/fc (Upper 2 bits = "01"), 16000/fc (Upper 2 bits = "11")

Fig. 1. Clock timing

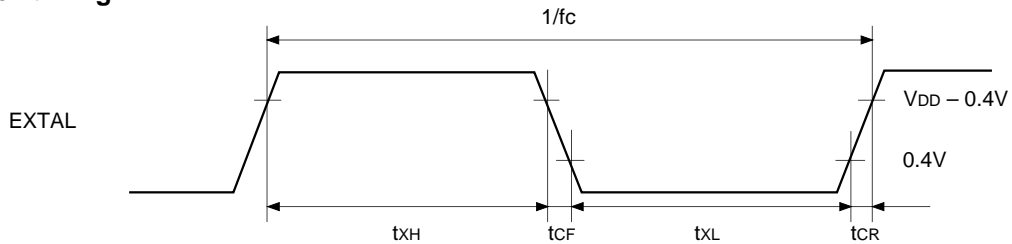


Fig. 2. Clock applying condition

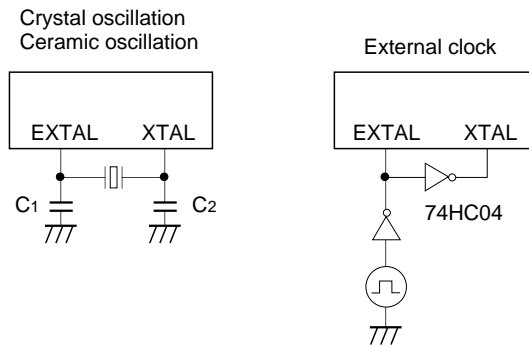
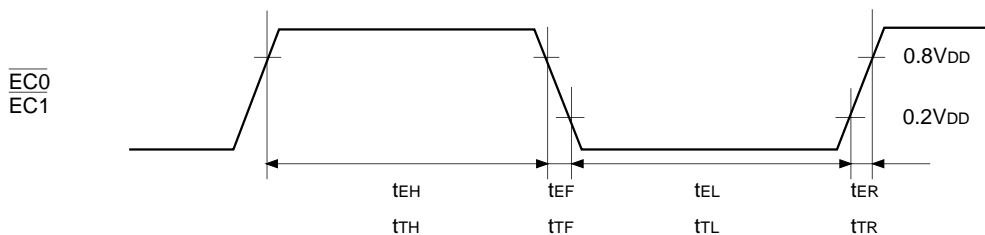


Fig. 3. Event count clock timing



(2) Serial transfer (CH0)

(Ta = -20 to +75°C, VDD = 4.5 to 5.5V, VSS = 0V)

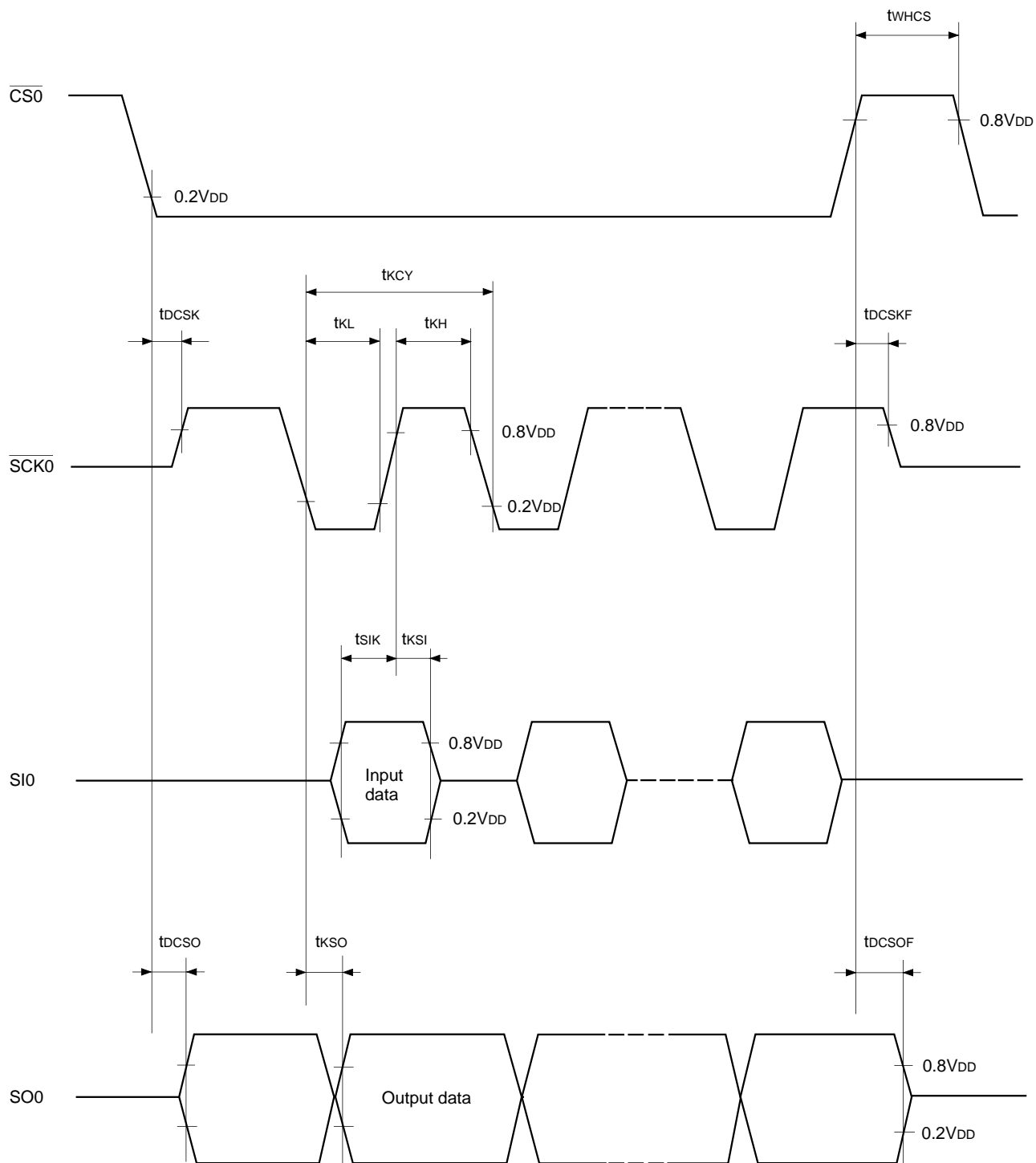
Item	Symbol	Pin	Condition	Min.	Max.	Unit
$\overline{CS0} \downarrow \rightarrow \overline{SCK0}$ delay time	t _{DCSK}	$\overline{SCK0}$	Chip select transfer mode ($\overline{SCK0}$ = output mode)		t _{sys} + 200	ns
$\overline{CS0} \uparrow \rightarrow \overline{SCK0}$ float delay time	t _{DCSKF}	$\overline{SCK0}$	Chip select transfer mode ($\overline{SCK0}$ = output mode)		t _{sys} + 200	ns
$\overline{CS0} \downarrow \rightarrow SO0$ delay time	t _{DCSO}	SO0	Chip select transfer mode		t _{sys} + 200	ns
$\overline{CS0} \uparrow \rightarrow SO0$ float delay time	t _{DCSOF}	SO0	Chip select transfer mode		t _{sys} + 200	ns
$\overline{CS0}$ high level width	t _{WHCS}	$\overline{CS0}$	Chip select transfer mode	t _{sys} + 200		ns
$\overline{SCK0}$ cycle time	t _{KCY}	$\overline{SCK0}$	Input mode	2t _{sys} + 200		ns
			Output mode	16000/fc		ns
$\overline{SCK0}$ high and low level width	t _{KH} t _{KL}	$\overline{SCK0}$	Input mode	t _{sys} + 100		ns
			Output mode	8000/fc - 50		ns
SI0 input setup time (against $\overline{SCK0} \uparrow$)	t _{SIK}	SI0	$\overline{SCK0}$ input mode	100		ns
			$\overline{SCK0}$ output mode	200		ns
SI0 input hold time (against $\overline{SCK0} \uparrow$)	t _{KSI}	SI0	$\overline{SCK0}$ input mode	t _{sys} + 200		ns
			$\overline{SCK0}$ output mode	100		ns
$\overline{SCK0} \downarrow \rightarrow SO0$ delay time	t _{KSO}	SO0	$\overline{SCK0}$ input mode		t _{sys} + 200	ns
			$\overline{SCK0}$ output mode		100	ns

Note 1) t_{sys} is determined by the upper two bits of the clock control register (Address: 00FEH; CPU clock selected) resulting in one of the 3 following values:

t_{sys} [ns] = 2000/fc (Upper 2 bits = "00"), 4000/fc (Upper 2 bits = "01"), 16000/fc (Upper 2 bits = "11")

Note 2) The load of $\overline{SCK0}$ output mode and SO0 output delay time is 50pF + 1TTL.

Fig. 4. Serial transfer CH0 timing



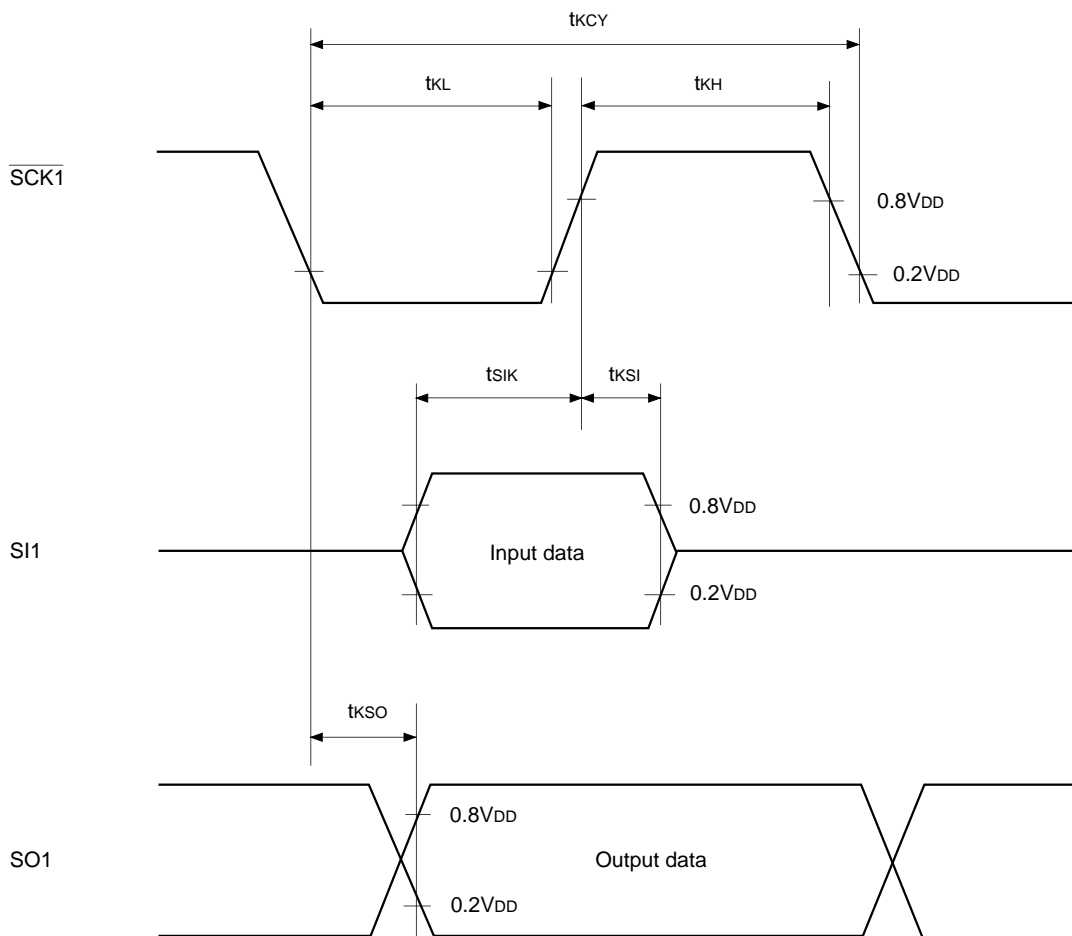
Serial transfer (CH1)

($T_a = -20$ to $+75^\circ\text{C}$, $V_{DD} = 4.5$ to 5.5V , $V_{SS} = 0\text{V}$)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
$\overline{\text{SCK1}}$ cycle time	t_{KCY}	$\overline{\text{SCK1}}$	Input mode	1000		ns
			Output mode	$16000/f_c$		ns
$\overline{\text{SCK1}}$ high and low level width	t_{KH} t_{KL}	$\overline{\text{SCK1}}$	Input mode	400		ns
			Output mode	$8000/f_c - 50$		ns
SI1 input setup time (against $\overline{\text{SCK1}} \uparrow$)	t_{SIK}	SI1	$\overline{\text{SCK1}}$ input mode	100		ns
			$\overline{\text{SCK1}}$ output mode	200		ns
SI1 input hold time (against $\overline{\text{SCK1}} \uparrow$)	t_{KSI}	SI1	$\overline{\text{SCK1}}$ input mode	200		ns
			$\overline{\text{SCK1}}$ output mode	100		ns
$\overline{\text{SCK1}} \downarrow \rightarrow \text{SO1}$ delay time	t_{KSO}	SO1	$\overline{\text{SCK1}}$ input mode		200	ns
			$\overline{\text{SCK1}}$ output mode		100	ns

Note) The load of $\overline{\text{SCK1}}$ output mode and SO1 output delay time is $50\text{pF} + 1\text{TTL}$.

Fig. 5. Serial transfer CH1 timing

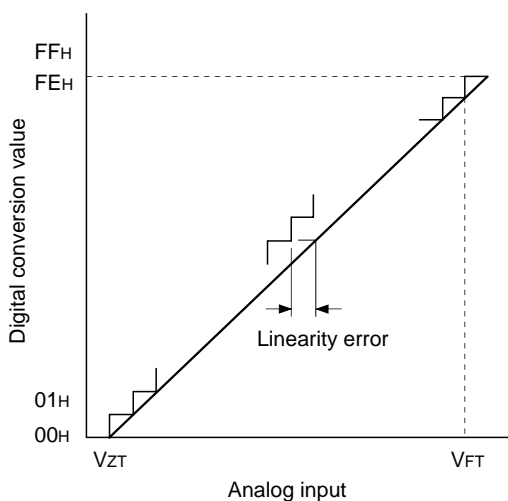


(3) A/D converter characteristics

($T_a = -20$ to $+75^\circ\text{C}$, $V_{DD} = 4.5$ to 5.5V , $V_{SS} = 0\text{V}$)

Item	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit
Resolution						8	Bits
Linearity error			A/D converter operation only $T_a = 25^\circ\text{C}$ $V_{DD} = 5.0\text{V}$ $V_{SS} = 0\text{V}$			± 3	LSB
Zero transition voltage	V_{ZT}^{*1}			-10	70	150	mV
Full-scale transition voltage	V_{FT}^{*2}			4930	5050	5120	mV
Conversion time	t_{CONV}			$160/f_{ADC}^{*3}$			μs
Sampling time	t_{SAMP}			$12/f_{ADC}^{*3}$			μs
Analog input voltage	V_{IAN}	AN0 to AN7		0		V_{DD}	V

Fig. 6. Definition of A/D converter terms



- *1 V_{ZT} : Digital Value converted between 00H to 01H.
- *2 V_{FT} : Digital Value converted between FEH and FFH.
- *3 f_{ADC} : ADC operation clock selection (MSC: Bit 0 of address 01FFH) and assumes following values:
 $f_{ADC} = f_c/2$ when PS2 is selected.
 $f_{ADC} = f_c$ when PS1 is selected.

(4) Interrupts, reset inputs (Ta = -20 to +75°C, VDD = 4.5 to 5.5V, VSS = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
External interrupt High and Low level widths	t _{IH} t _{IL}	INT0 INT1 INT2 INT3		1		μs
Reset input Low level width	t _{RSL}	$\overline{\text{RST}}$		8/fc		μs

Fig. 7. Interrupt input timing

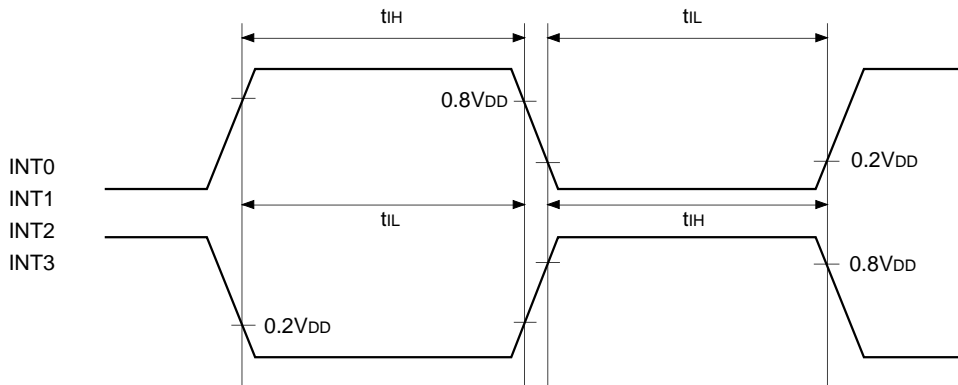
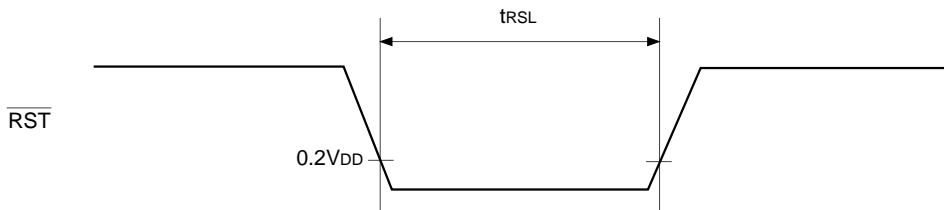


Fig. 8. $\overline{\text{RST}}$ input timing



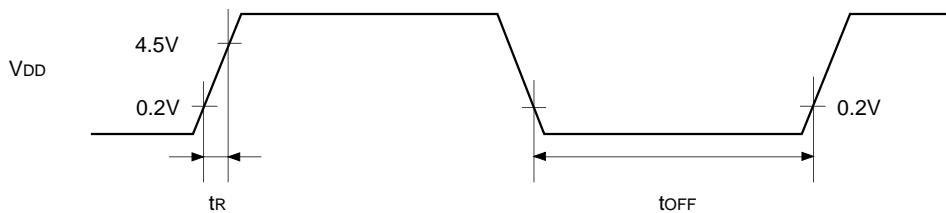
(5) Power-on reset

Power-on reset* (Ta = -20 to +75°C, VDD = 4.5 to 5.5V, VSS = 0V)

Item	Symbol	Pin	Condition	Min.	Max.	Unit
Power supply rising time	t _R	V _{DD}	Power-on reset	0.05	50	ms
Power supply cut-off time	t _{OFF}		Repetitive power-on reset	1		ms

* Specifies only when power-on reset function is selected.

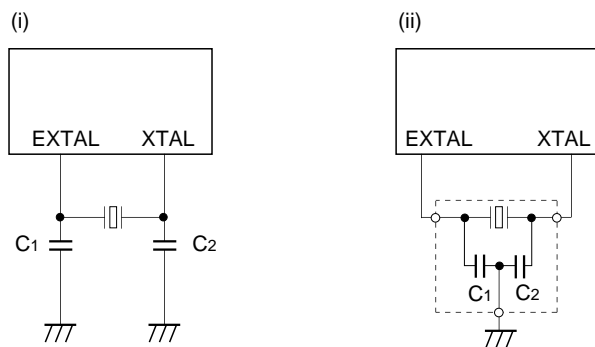
Fig. 9. Power-on reset



The power supply should be rise smoothly.

Supplement

Fig. 10. Recommended Oscillation Circuit

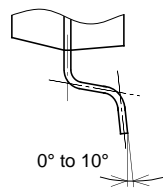
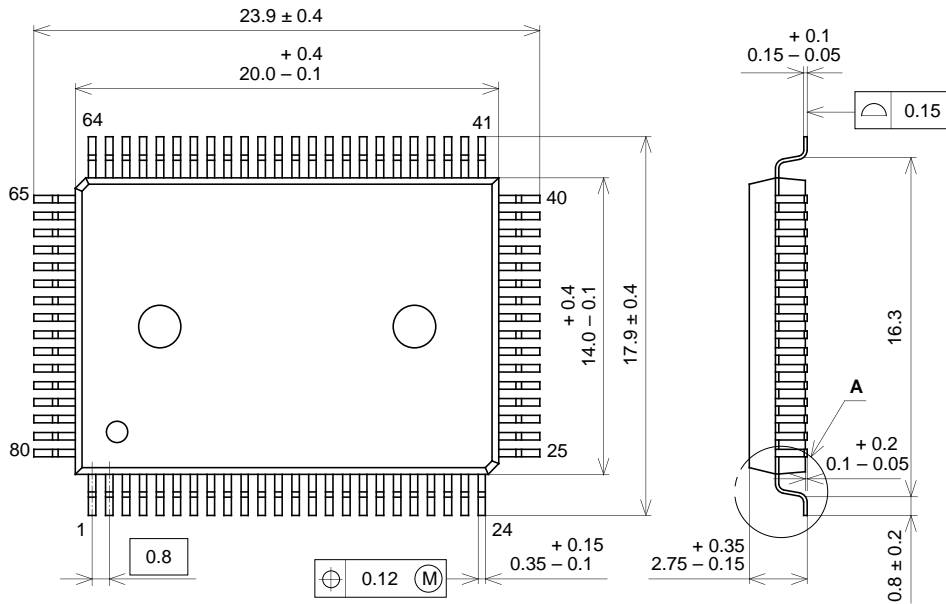


Manufacturer	Model	fc (MHz)	C ₁ (pF)	C ₂ (pF)	Circuit Example
MURATA MFG CO., LTD	CSA4.19MG	4.19	30	30	(i)
	CSA8.00MG	8.00			
	CSA10.0MT	10.00			
	CST4.19MGW*	4.19			(ii)
	CST8.00MTW*	8.00			
	CST10.00MTW*	10.00			
FUJI SANGYO CO., LTD	HC-49/U03	4.19	15	15	(i)
		8.00			
		10.00			
KINSEKI LTD.	HC-49/U (-S)	4.19	27	27	
		8.00			
		10.00			

* Indicates types with on-chip grounding capacitors (C₁ and C₂).

Package Outline Unit: mm

80PIN QFP (PLASTIC)



DETAIL A

SONY CODE	QFP-80P-L01
EIAJ CODE	QFP080-P-1420
JEDEC CODE	_____

PACKAGE STRUCTURE

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	1.6g